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PRODUCT CHANGE NOTIFICATION

PCN: PCN145320

Date: June 18, 2014

Subject: Qualification of Copper Palladium Wire Bonds for Select Lead Frame Products at JCET China

To: PCN ADMIN
CYPRESS
pcn_admin@cypress.com

Change Type: Major

Description of Change:

Cypress announces the qualification of Copper Palladium (CuPd) wire bonds for select lead frame (LF) products at Jiangsu Changjiang Electronics Technology Co., Ltd (JCET) in China using the Bill of Materials in the attached table. There will be no changes to product datasheets or part numbers.

JCET is the largest provider of independent semiconductor manufacturing services for assembly and test in China. Their assembly facility in Changjiang, China is already a qualified assembly site for Cypress products. JCET is certified on several international quality standards: ISO/TS16949: 2009, ANSI/ESD S20.20:2007, IECQ QC 080000:2005, ISO14001 and OHSAS18001.

Benefit of Change:

The conversion to CuPd wire bonds will keep Cypress in alignment with the overall industry trend towards copper palladium wire bonds. This also provides the means for Cypress to continue to meet customers' varied packaging needs as well as delivery commitments in dynamic, changing market conditions.

Affected Part Numbers: 565

Affected Parts:

See the attached file for a list of all part numbers affected by this change. Note that any new lead frame parts in these packages that are introduced after the publication of this PCN will also be manufactured with either CuPd or gold wire bonds.

Qualification Status:

CuPd wire bonds have been qualified through a series of tests documented in the Qualification Test Plan (QTP) reports indicated in the table below. Qualification reports can be found as attachments to this notification or by visiting www.cypress.com and typing the QTP number in the keyword search window.

| Package Description | QTP Number |
|----------------------------|-------------------|
| 128 lead (14x20) TQFP | 141302 |
| 100 lead (14x20) TQFP | 141302 |
| 100 lead (14x14) TQFP | 141302 |
| 64 lead (14x14) TQFP | 141302 |
| 44 lead (10x10) TQFP | 141302 |
| 44 lead 400 mil TSOPII | 141303 |
| 32 lead 300 mil STSOP | 141303 |
| 28 lead 300 mil TSOP | 141303 |

Sample Status:

Qualification samples are not built ahead of time for all part numbers affect by this change. Please review the attached file for a list of affected part numbers with their associated sample ordering part numbers. Sample requests for products without sample order part numbers are not built ahead of time, will be built to order and subject to standard lead times. Please contact your sales representative as soon as possible, but within 30 days of the date of this PCN, to place any sample orders.

Approximate Implementation Date:

Effective 90 days from the date of this notification or upon customer approval, whichever comes first, all shipments of the affected part numbers in the attached file will be supplied with either CuPd wire bonds or gold wire bonds.

Anticipated Impact:

Products manufactured with CuPd wire bonds are completely compatible with existing product from a functional, parametric, and quality performance perspective.

Cypress recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:

There will be no changes to the part number. A "C" will be added to the package marking to designate CuPd wire bonds. Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration

